CMOS IC 16K-byte FROM and 1024-byte RAM integrated 8-bit 1-chip Microcontroller with Full-Speed USB

Overview

The LC87F1M16A is an 8-bit microcomputer that, integrates on a single chip a number of hardware features such as 16K-byte flash ROM, 1024-byte RAM, an on-chip debugger, a16-bit timer/counter, a 16-bit timer, four 8-bit timers, a base timer serving as a time-of-day clock, two channels of synchronous SIO interface (with automatic block transmission/reception capabilities), an asynchronous/synchronous SIO interface, a UART interface, a UART interface function, a full-speed USB interface (function), a 20-channel AD converter (12- or 8-bit resolution selectable), 2 channels of 12-bit PWM, a system clock frequency divider, an internal reset and an interrupt feature.

Features

Flash ROM

- 16384 × 8 bits
- Capable of on-board programming with a wide range of supply voltages: 3.0 to 5.5V
- Block-erasable in 128 byte units
- Writes data in 2-byte units

■RAM

• 1024×9 bits

■Package Form

• SQFP48 (7×7): Lead-/Halogen-free type

Package Dimensions



* This product is licensed from Silicon Storage Technology, Inc. (USA).



■Bus Cycle Time

• 83.3ns (When CF=12MHz)

Note: The bus cycle time here refers to the ROM read speed.

- ■Minimum Instruction Cycle Time (tCYC)
 - 250ns (When CF=12MHz)

■Ports

• I/O ports

Ports whose I/O direction can be designated in 1-bit units	35 (P00 to P07, P10 to P17, P20 to P27, P31 to P34,
	P70 to P73, PWM0, PWM1, XT2)

• USB ports	2 (D+, D-)
 Dedicated oscillator ports 	2 (CF1, CF2)
• Input-only port (also used for oscillation)	1 (XT1)
• Reset pins	$1(\overline{\text{RES}})$
 Dedicated debugger port 	1 (OWP0)
• Power supply pins	6 (VSS1 to 3, VDD1 to 3)

- ■Timers
 - Timer 0: 16-bit timer/counter with 2 capture registers.
 - Mode 0: 8-bit timer with an 8-bit programmable prescaler (with two 8-bit capture registers) × 2 channels Mode 1: 8-bit timer with an 8-bit programmable prescaler (with two 8-bit capture registers)
 - + 8-bit counter (with two 8-bit capture registers)
 - Mode 2: 16-bit timer with an 8-bit programmable prescaler (with two 16-bit capture registers)
 - Mode 3: 16-bit counter (with two 16-bit capture registers)
 - Timer 1: 16-bit timer/counter that supports PWM/toggle outputs

Mode 0: 8-bit timer with an 8-bit prescaler (with toggle outputs) + 8-bit timer/

- counter with an 8-bit prescaler (with toggle outputs)
- Mode 1: 8-bit PWM with an 8-bit prescaler \times 2 channels
- Mode 2: 16-bit timer/counter with an 8-bit prescaler (with toggle outputs)
 - (toggle outputs also possible from lower-order 8 bits)
- Mode 3: 16-bit timer with an 8-bit prescaler (with toggle outputs)
 - (lower-order 8 bits may be used as a PWM output)
- Timer 4: 8-bit timer with a 6-bit prescaler
- Timer 5: 8-bit timer with a 6-bit prescaler
- Timer 6: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Timer 7: 8-bit timer with a 6-bit prescaler (with toggle outputs)
- Base timer
 - (1) The clock is selectable from the subclock (32.768kHz crystal oscillation), system clock, and timer 0 prescaler output.
 - (2) Interrupts programmable in 5 different time schemes

■SIO

- SIO0: Synchronous serial interface
 - (1) LSB first/MSB first mode selectable
 - (2) Transfer clock cycle: 4/3 to 512/3 tCYC
 - (3) Automatic continuous data transmission (1 to 256 bits, specifiable in 1-bit units) (Suspension and resumption of data transmission possible in 1 byte units)
- SIO1: 8-bit asynchronous/synchronous serial interface
 - Mode 0: Synchronous 8-bit serial I/O (2- or 3-wire configuration, 2 to 512 tCYC transfer clocks)
 - Mode 1: Asynchronous serial I/O (half-duplex, 8 data bits, 1 stop bit, 8 to 2048 tCYC baudrates)
 - Mode 2: Bus mode 1 (start bit, 8 data bits, 2 to 512 tCYC transfer clocks)
 - Mode 3: Bus mode 2 (start detect, 8 data bits, stop detect)
- SIO4: Synchronous serial interface
 - (1) LSB first/MSB first mode selectable
 - (2) Transfer clock cycle: 4/3 to 1020/3 tCYC
 - (3) Automatic continuous data transmission (1 to 1024 bytes, specifiable in 1 byte units, suspension and resumption of data transmission possible in 1 byte or 2 bytes units)
 - (4) Clock polarity selectable
 - (5) CRC16 calculator circuit built in

■Full Duplex UART

• UART1

- (1) Data length : 7/8/9 bits selectable
- (2) Stop bits : 1 bit (2 bits in continuous transmission mode)
- (3) Baud rate : 16/3 to 8192/3 tCYC
- SCUART
 - (1) Data length : 7/8 bits selectable
 - (2) Stop bits : 1/2 bits selectable
 - (3) Parity bits : None/even parity/odd parity
 - (4) Baud rate : 8/3 to 8192/3 tCYC
 - (5) LSB first/MSB first mode delectable
 - (6) Smartcard interface function

■AD Converter: 12 bits × 20 channels

- 12-/8-bit resolution selectable AD converter
- ■PWM: Multifrequency 12-bit PWM × 2 channels
- ■USB Interface (function controller)
 - (1) Compliant with USB 2.0 Full-Speed

(2) Supports a maximum of 6 user-defined endpoints.

	Endpoint		EP1	EP2	EP3	EP4	EP5	EP6
Transfer	Control	0	-	-	-	-	-	-
Туре	Bulk	-	0	0	0	0	0	0
	Interrupt	-	0	0	0	0	0	0
	Isochronous	-	0	0	0	0	0	0
Max. paylo	bad	64	64	64	64	64	64	64

■Watchdog Timer

• Internal counter watchdog timer

- (1) Generates an internal reset on an overflow occurring in the timer running on the low-speed RC oscillator clock (approx. 30kHz) or subclock.
- (2) Operating mode at HALT/HOLD mode is selectable from 3 modes(continue counting/suspend operation/suspend counting with the count value retained)

■Clock Output Function

- (1) Can output a clock with a clock rate of 1/1, 1/2, 1/4, 1/8, 1/16, 1/32, or 1/64 of the source oscillator clock selected as the system clock.
- (2) Can output the source oscillation clock for the subclock.

■Interrupts

- 35 sources, 10 vector addresses
 - (1) Provides three levels (low (L), high (H), and highest (X)) of multiplex interrupt control. Any interrupt requests of the level equal to or lower than the current interrupt are not accepted.
 - (2) When interrupt requests to two or more vector addresses occur at the same time, the interrupt of the highest level takes precedence over the other interrupts. For interrupts of the same level, the interrupt into the smallest vector address takes precedence.

No.	Vector Address	Level	Interrupt Source
1	00003H	X or L	INTO
2	0000BH	X or L	INT1
3	00013H	H or L	INT2/T0L/INT4/USB bus active
4	0001BH	H or L	INT3/INT5/base timer
5	00023H	H or L	T0H/INT6
6	0002BH	H or L	T1L/T1H/INT7
7	00033H	H or L	SIO0/USB bus reset/USB suspend/UART1 receive complete/ SCUART receive complete
8	0003BH	H or L	SIO1/USB endpoint/USB-SOF/SIO4/ UART1 buffer empty/UART1 transmit complete/ SCUART buffer empty/SCUART transmit complete
9	00043H	H or L	ADC/T6/T7
10	0004BH	H or L	Port 0/PWM0/PWM1/T4/T5

• Priority levels X > H > L

• Of interrupts of the same level, the one with the smallest vector address takes precedence.

Subroutine Stack Levels: 512 levels maximum (The stack is allocated in RAM.)

■High-speed Multiplication/Division Instructions

- 16 bits \times 8 bits (5 tCYC execution time)
- 24 bits \times 16 bits (12 tCYC execution time)
- 16 bits ÷ 8 bits (8 tCYC execution time)
- 24 bits ÷ 16 bits (12 tCYC execution time)

■Oscillation and PLL Circuits

- RC oscillation circuit (internal) : For system clock (approx. 1MHz)
- Low-speed RC oscillation circuit (internal) : For watchdog timer (approx. 30kHz)
- CF oscillation circuit

- : For system clock
- Crystal oscillation circuit
- PLL circuit (internal)
- : For system clock, time-of-day clock
- : For USB interface (see Fig.5)

■Internal Reset Circuit

- •Power-on reset (POR) function
 - (1) POR reset is generated only at power-on time.
- (2) The POR release level can be selected from 4 levels (2.57V, 2.87V, 3.86V and 4.35V) through option configuration.
- •Low-voltage detection reset (LVD) function
 - (1) LVD and POR functions are combined to generate resets when power is turned on and when power voltage falls below a certain level.
 - (2) The use/disuse of the LVD function and the voltage threshold level can be selected from 3 levels (2.81V, 3.79V and 4.28V) through option configuration.

■Standby Function

- HALT mode: Halts instruction execution while allowing the peripheral circuits to continue operation.
 - (1) Oscillation is not halted automatically.
 - (2) There are three ways of resetting the HOLD mode.
 - 1) Setting the reset pin to the lower level
 - 2) Having the watchdog timer or LVD function generate a reset
 - 3) Having an interrupt generated
- HOLD mode: Suspends instruction execution and the operation of the peripheral circuits.
 - (1) The PLL base clock generator, CF, RC and crystal oscillators automatically stop operation.
 - Note: The low-speed RC oscillator is controlled directly by the watchdog timer; its oscillation in the standby mode is also controlled by the watchdog timer.
 - (2) There are five ways of resetting the HOLD mode.
 - 1) Setting the reset pin to the lower level
 - 2) Having the watchdog timer or LVD function generate a reset
 - 3) Having an interrupt source established at one of the INT0, INT1, INT2, INT4 or INT5 pins
 - * INT0 and INT1 HOLD mode reset is available only when level detection is set.
 - 4) Having an interrupt source established at port 0
 - 5) Having an bus active interrupt source established in the USB interface circuit
- X'tal HOLD mode: Suspends instruction execution and the operation of the peripheral circuits except the base timer.
 - (1) The PLL base clock generator, CF and RC oscillator automatically stop operation.
 - Note: The low-speed RC oscillator is controlled directly by the watchdog timer; its oscillation in the standby mode is also controlled by the watchdog timer.
 - (2) The state of crystal oscillation established when the X'tal HOLD mode is entered is retained.
 - (3) There are six ways of resetting the X'tal HOLD mode.
 - 1) Setting the reset pin to the low level
 - 2) Having the watchdog timer or LVD function generate a reset
 - 3) Having an interrupt source established at either INT0, INT1, INT2, INT4 or INT5 * INT0 and INT1 HOLD mode reset is available only when level detection is set.
 - 4) Having an interrupt source established at port 0
 - 5) Having an interrupt source established in the base timer circuit
 - 6) Having an bus active interrupt source established in the USB interface circuit

■Development Tools

• On-chip debugger: TCB87 type-C (one wire communication cable) + LC87F1M16A

■Flash ROM Programming Boards

Package	Programming boards
SQFP48(7×7)	W87F55256SQ

■Flash Programmer

Make	r	Supported version	Device	
Flash Support Group, Inc. (FSG)	Single Programmer	AF9709/AF9709B/AF9709C (Including Ando Electric Co., Ltd. models)	Rev 03.32 or later	87F016JU
Flash Support Group, Inc.	Onboard	AF9101/AF9103(Main unit) (FSG models)		
(FSG) + Our company (Note 1)	Single/Gang Programmer	SIB87(Inter Face Driver) (Our company model)	(Note 2)	LC87F1M16A
	Single/Gang Programmer	SKK/SKK Type B (SanyoFWS)	Application Version	
Our company	Onboard Single/Gang Programmer	SKK-DBG Type C (SanyoFWS)	1.06 or later Chip Data Version 2.31 or later	LC87F1M16

For information about AF-Series: Flash Support Group, Inc. TEL: +81-53-459-1050 E-mail: <u>sales@j-fsg.co.jp</u>

Note1: On-board-programmer from FSG (AF9101/AF9103) and serial interface driver from Our company (SIB87) together can give a PC-less, standalone on-board-programming capabilities.

Note2: It needs a special programming devices and applications depending on the use of programming environment. Please ask FSG or Our company for the information.



SQFP48(7×7) "Lead-/Halogen-free Type"

SQFP48	NAME
25	P04/AN4
26	P05/AN5/CKO
27	P06/AN6/T6O
28	P07/AN7/T7O
29	P20/INT4/INT6/AN12/UTX1
30	P21/INT4/AN13/URX1
31	P22/INT4/AN14/SO4
32	P23/INT4/AN15/SI4
33	P24/INT5/INT7/AN16/SCK4
34	P25/INT5/AN17
35	P26/INT5/AN18
36	P27/INT5/AN19/DPUP2
37	D-
38	D+
39	V _{DD} 3
40	V _{SS} 3
41	P34/UFILT
42	P33
43	P32/SCRX
44	P31/SCTX
45	OWP0
46	P70/INT0/T0LCP/DPUP
47	P71/INT1/T0HCP
48	P72/INT2/T0IN

SQFP48	NAME
1	P73/INT3/T0IN
2	RES
3	XT1/AN10
4	XT2/AN11
5	V _{SS} 1
6	CF1
7	CF2
8	V _{DD} 1
9	P10/SO0
10	P11/SI0/SB0
11	P12/SCK0
12	P13/SO1
13	P14/SI1/SB1
14	P15/SCK1
15	P16/T1PWML
16	P17/T1PWMH/BUZ
17	PWM1/AN8/TDN0
18	PWM0/AN9/TDP0
19	V _{DD} 2
20	V _{SS} 2
21	P00/AN0/TDN1
22	P01/AN1/TDP1
23	P02/AN2/TDN2
24	P03/AN3

System Block Diagram



Pin Description

Pin Name	I/O			Des	scription			Option	
V _{SS} 1,V _{SS} 2, V _{SS} 3	-	- Power supply							
V _{DD} 1, V _{DD} 2	-	+ Power supply	No						
V _{DD} 3	-	USB reference	voltage					Yes	
Port 0	I/O	8-bit I/O ports						Yes	
P00 to P07		 I/O specifiable 	e in 1-bit units						
				d on and off in 1	-bit units				
		HOLD reset in	•						
		 Port 0 interrup Pin functions 	ot input						
			input ports: ANO	to AN7(P00 to	P07)				
			rent Nch driver(107)				
		-	rent Pch driver(1	-					
		-	rent Nch driver(
		P05: System of	clock output						
		P06: Timer 6 f							
		P07: Timer 7 t	oggle output						
Port 1	I/O	8-bit I/O port						Yes	
P10 to P17		I/O specifiable			1.14				
		 Pull-up resistor Pin functions 	rs can be turned	a on and off in 1	-dit units				
		• Pin functions P10: SIO0 dat							
			a input/bus I/O						
		P12: SIO0 clo	-						
		P13: SIO1 dat	a output						
		P14: SIO1 dat							
		P15: SIO1 clo	ck I/O						
		P16: Timer 1	-						
			PWMH output/b	eeper output					
Port 2	I/O	8-bit I/O ports						Yes	
P20 to P27		I/O specifiable Pull-up resister		d on and off in 1	-bit unite				
		Pin functions							
			input ports: AN1	2 to AN19(P20	to P27)				
				-	r 1 event input/ti	mer 0L capture i	nput/		
		tii	mer 0H capture	input					
		P24 to P27: IN	IT5 input/HOLD	reset input/time	r 1 event input/ti	mer 0L capture i	nput/		
			mer 0H capture	•					
		-	-	ure 1 input/UAR	T1 transmit				
		P21: UART1 r							
		P22: SIO4 dat P23: SIO4 dat							
				ure 1 input/SIO4	t clock I/O				
		-	2 pull-up resisto	-					
		Interrupt ackn	owledge types	-					
			Rising	Falling	Rising & Falling	H level	L level		
		INT4	enable	enable	enable	disable	disable		
		INT5	enable	enable	enable	disable	disable		
		INT6	enable	enable	enable	disable	disable		
		INT7	enable	enable	enable	disable	disable		
Port 3	I/O	4-bit I/O ports						Yes	
P31 to P34	1	I/O specifiable							
-				d on and off in 1	-bit units				
Pin functions P31: SCUART transmit									
		P32: SCUART	receive						

Continued on next page.

Pin Name	I/O			Desc	ription			Option
Port 7	I/O	4-bit I/O port						No
P70 to P73		• I/O specifiable	in 1-bit units					
		Pull-up resistor	s can be turned	on and off in 1-b	oit units			
		 Pin functions 						
		P70: INT0 input	t/HOLD reset inp	out/timer 0L capt	ure input/ D+ 1.	5kΩ pull-up resi	stor connect pin	
		P71: INT1 input	t/HOLD reset inp	out/timer 0H cap	ture input			
		P72: INT2 input	t/HOLD reset inp	out/timer 0 event	input/timer 0L o	capture input/		
		. .	d clock counter i	•				
		P73: INT3 input	t (input with nois	e filter)/timer 0 e	event input/timer	0H capture inpu	ut	
		Interrupt acknow	wledge types		[1	1	
			Rising	Falling	Rising &	H level	L level	
			Ŭ		Falling			
		INT0	enable	enable	disable	enable	enable	
		INT1	enable	enable	disable	enable	enable	
		INT2	enable	enable	enable	disable	disable	
		INT3	enable	enable	enable	disable	disable	
PWM0	I/O	• PWM0, PWM1	output port					No
PWM1		Pin functions						
		General-purpose input ports						
		AD converter in	put ports: AN8(F	PWM1), AN9(PV	VM0)			
		5	Irrent Pch driver	, ,				
			Irrent Nch driver	(TDN0)				
D-	I/O	USB data I/O p						No
		General-purpos	•					
D+	I/O	• USB data I/O p						No
RES		General-purpos						N
-	Input	External reset inp						No
XT1	Input	• 32.768kHz crys	stal oscillator inp	ut				No
		Pin functions						
		General-purpos						
XT2	I/O		put ports: AN10	out				No
X12	1/0	32.768kHz crystal oscillator output						INO
		 Pin functions General-purpos 						
		AD converter input port: AN11						
CF1	Input		• •					No
CF1 CF2	Input Output	Ceramic resonate	or input					No No

On-chip Debugger Pin Connection Requirements

For the treatment of the on-chip debugger pins, refer to the separately available documents entitled "Rd87 On-chip Debugger Installation Manual"

Recommended Unused Pin Connections

Port Name	Recommended Unused Pin Connections					
Port Name	Board	Software				
P00 to P07	Open	Output low				
P10 to P17	Open	Output low				
P20 to P27	Open	Output low				
P31 to P34	Open	Output low				
P70 to P73	Open	Output low				
PWM0, PWM1	Open	Output low				
D+, D-	Open	Output low				
XT1	Pulled low with a $100k\Omega$ resistor or less	-				
XT2	Open	Output low				
OWP0	Pulled low with a $100k\Omega$ resistor	-				

Note: P34 and UFILT share the same pin, so if USB function is used, the pin must be set to input mode.

Port Output Types

The table below lists the types of port outputs and the presence/absence of a pull-up resistor.

Data can be read into any input port even if it is in the output mode.

Port Name	Option selected in units of	Option type	Output type	Pull-up resistor
P00 to P07	1 bit	1	CMOS	Programmable
P10 to P17				
P20 to P27		2	Nch-open drain	Programmable
P31 to P34				
P70	-	No	Nch-open drain	Programmable
P71 to P73	-	No	CMOS	Programmable
PWM0, PWM1	-	No	CMOS	No
D+, D-	-	No	CMOS	No
XT1	-	No	Input only	No
XT2	-	No	32.768kHz crystal resonator output (N channel open	No
			drain when in general-purpose output mode)	

User Option Table

Option Name	Option Type	Flash Version	Option Selected in Units of	Option Selection
Port output form	D00 to D07	a na bla	4 1-14	CMOS
	P00 to P07	$\left(\begin{array}{c} \ \ enable \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \$	Nch-open drain	
	D10 / D17		41.2	CMOS
	P10 to P17	enable	1 Dit	Nch-open drain
	D00 to D07	a sector	4 1-14	CMOS
	P20 to P27	enable	1 Dit	Nch-open drain
	D04 to D04	a sector	4 1-14	CMOS
	P31 to P34	enable	1 Dit	Nch-open drain
Program start		a sector		00000h
address	-	enable	-	03E00h
USB Regulator		a sector		USE
	USB Regulator	enable	-	NONUSE
	USB Regulator	a sector		USE
	(at HOLD mode)	enable	-	NONUSE
	USB Regulator	a sector		USE
	(at HALT mode)	enable	-	NONUSE
Main clock 8MHz				ENABLE
selection	-	enable	-	DISABLE
Low-voltage detection				Enable: Use
reset function	Detect function	enable	-	Disable: Not Used
	Detect level	enable	-	3-level
Power-on reset function	Power-On reset level	enable	-	4-level

USB Reference Power Option

When a voltage 4.5 to 5.5V is supplied to $V_{DD}1$ and the internal USB reference voltage circuit is activated, the reference voltage for USB port output is generated. The active/inactive state of the reference voltage circuit can be switched by option select. The procedure for marking the option selection is described below.

		(1)	(2)	(3)	(4)
Option settings	USB regulator	USE	USE	USE	NONUSE
	USB regulator at HOLD mode	USE	NONUSE	NONUSE	NONUSE
	USB regulator at HALT mode	USE	NONUSE	USE	NONUSE
Reference voltage circuit state	Normal mode	active	active	active	inactive
	HOLD mode	active	inactive	inactive	inactive
	HALT mode	active	inactive	active	inactive

• When the USB reference voltage circuit is made inactive, the level of the reference voltage for USB port output is equal to V_{DD}1.

• Selection (2) or (3) can be used to set the reference voltage circuit inactive in HOLD or HALT mode.

• When the reference voltage circuit is activated, the current drain increases by approximately 100µA compared with when the reference voltage circuit is inactive.

Example 1: VDD1=VDD2=3.3V

- Inactivating the reference voltage circuit (selection (4)).
- Connecting VDD3 to VDD1 and VDD2.



Example 2: VDD1=VDD2=5.0V

- Activating the reference voltage circuit (selection (1)).
- Isolating VDD3 from VDD1 and VDD2, and connecting capacitor between VDD3 and VSS.



Dor	rameter	Symbol	Pin/Remarks	Conditions			Specif	ication	
Fai	llameter	Symbol	FIN/Remaiks	Conditions	V _{DD} [V]	min	typ	max	unit
Maximu voltage	um supply	V _{DD} max	V _{DD} 1, V _{DD} 2, V _{DD} 3	V _{DD} 1= V _{DD} 2= V _{DD} 3		-0.3		+6.5	
Input vo	oltage	V _I (1)	XT1, CF1, RES			-0.3		V _{DD} +0.3	v
Input/ou voltage	•	V _{IO} (1)	Ports 0, 1, 2, 3, 7 PWM0, PWM1 XT2			-0.3		V _{DD} +0.3	
	eak output rrent	IOPH(1)	P00, P02 to P07 Ports 1, 2	When CMOS output type is selected Per 1 applicable pin		-10			
		IOPH(2)	PWM1	Per 1 applicable pin		-20			1
		IOPH(3)	PWM0(TDP0) P01(TDP1)	When CMOS output type is selected Per 1 applicable pin		-50			
	Average output current (Note 1-1)	IOPH(4)	Port 3 P71 to P73	When CMOS output type is selected Per 1 applicable pin		-5			
out		IOMH(1)	P00, P02 to P07 Ports 1, 2	When CMOS output type is selected Per 1 applicable pin		-7.5			
Irren		IOMH(2)	PWM1	Per 1 applicable pin		-15			
High level output current		IOMH(3)	PWM0(TDP0) P01(TDP1)	When CMOS output type is selected Per 1 applicable pin		-30			mA
High leve		IOMH(4)	Port 3 P71 to P73	When CMOS output type is selected Per 1 applicable pin		-3			
	otal output irrent	ΣIOAH(1)	P00, P02 to P07 Ports 2	Total current of all applicable pins		-25			
		ΣIOAH(2)	Port 1 PWM1	Total current of all applicable pins		-25			
		ΣIOAH(3)	PWM0(TDP0) P01(TDP1)	Total current of all applicable pins		-50			
		ΣIOAH(4)	Ports 0, 1, 2 PWM0, PWM1	Total current of all applicable pins		-100			
		ΣIOAH(5)	Port 3 P71 to P73	Total current of all applicable pins		-10			
		ΣIOAH(6)	D+, D-	Total current of all applicable pins		-25			

Absolute Maximum Ratings at $Ta = 25^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Note 1-1: The average output current is an average of current values measured over 100ms intervals.

Continued on next page.

	Demonster	Ourseland.	Dia /D a sea a star	O a setti a sa			Specific	cation	
	Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	Peak output current	IOPL(1)	P03 to P07 Ports 1, 2 PWM0	Per 1 applicable pin				20	
		IOPL(2)	P01	Per 1 applicable pin				30	
		IOPL(3)	PWM1(TDN0) P00(TDN1) P02(TDN2)	Per 1 applicable pin				50	
		IOPL(4)	Ports 3, 7 XT2	Per 1 applicable pin				10	
	Average output current (Note 1-1)	IOML(1)	P03 to P07 Ports 1, 2 PWM0	Per 1 applicable pin				15	
ent		IOML(2)	P01	Per 1 applicable pin				20	1
Low level output current		IOML(3)	PWM1(TDN0) P00(TDN1) P02(TDN2)	Per 1 applicable pin				30	mA
ow level c	T	IOML(4)	Ports 3, 7 XT2	Per 1 applicable pin				7.5	
Lo	Total output current	ΣIOAL(1)	P01, P03 to P07 Ports 2	Total current of all applicable pins				45	
		ΣIOAL(2)	Port 1 PWM0	Total current of all applicable pins				45	
		ΣIOAL(3)	PWM1(TDN0) P00(TDN1) P02(TDN2)	Total current of all applicable pins				50	
		ΣIOAL(4)	Ports 0, 1, 2 PWM0, PWM1	Total current of all applicable pins				140	
		ΣIOAL(5)	Ports 3, 7 XT2	Total current of all applicable pins				15	
		ΣIOAL(6)	D+, D-	Total current of all applicable pins				25	
All	owable power	Pd max	SQFP48(7×7)	Ta=-30 to +70°C				190	
Di	ssipation			Ta=-40 to +85°C				140	mV
	perating ambient mperature	Topr				-40		+85	°C
	orage ambient nperature	Tstg				-55		+125	Ű

Note 1-1: The average output current is an average of current values measured over 100ms intervals.

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Parameter	Symbol	Din/Domorko	Conditions			Specific	ation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Operating	V _{DD} (1)	V _{DD} 1=V _{DD} 2=V _{DD} 3	$0.245 \mu s \leq tCYC \leq 200 \mu s$		3.0		5.5	
supply voltage (Note 2-1)			$0.490\mu s \le tCYC \le 200\mu s$ Except in onboard programming mode		2.7		5.5	
			0.245μs ≤ CYC ≤ 0.383μs USB circuit active		3.0		5.5	
Memory sustaining supply voltage	VHD	V _{DD} 1=V _{DD} 2=V _{DD} 3	RAM and register contents sustained in HOLD mode.		2.0		5.5	
High level input voltage	V _{IH} (1)	Port 0, 1, 2, 3, 7 PWM0, PWM1		2.7 to 5.5	0.3V _{DD} +0.7		V _{DD}	v
	V _{IH} (2)	XT1, XT2, CF1, RES		2.7 to 5.5	0.75V _{DD}		V _{DD}	
Low level input voltage	V _{IL} (1)	Port 1, 2, 3, 7		4.0 to 5.5	V _{SS}		0.1V _{DD} +0.4	
	V _{IL} (2)			2.7 to 4.0	VSS		0.2V _{DD}	
	V _{IL} (3)	Port 0 PWM0, PWM1		4.0 to 5.5	V _{SS}		0.15V _{DD} +0.4	
	V _{IL} (4)			2.7 to 4.0	V _{SS}		0.2V _{DD}	
	V _{IL} (5)	XT1, XT2, CF1, RES		2.7 to 5.5	VSS		0.25V _{DD}	
Instruction	tCYC			3.0 to 5.5	0.245		200	
cycle time (Note 2-2)			Except for onboard programming mode	2.7 to 5.5	0.490		200	μs
			USB circuit active	3.0 to 5.5	0.245		0.383	
External system clock frequency	FEXCF(1)	CF1	 CF2 pin open System clock frequency division ratio=1/1 External system clock duty =50±5% 	3.0 to 5.5	0.1		12	
			 CF2 pin open System clock frequency division ratio=1/1 External system clock duty =50±5% 	2.7 to 5.5	0.1		6	MHz
Oscillation frequency	FmCF	CF1, CF2	When 12MHz ceramic oscillation See Fig. 1.	3.0 to 5.5		12		MHz
range	FmRC		Internal RC oscillation	2.7 to 5.5	0.5	1.0	2.0	
(Note 2-3)	FmSLRC		Internal low-speed RC oscillation	2.7 to 5.5	15	30	60	
	FsX'tal	XT1, XT2	32.768kHz crystal oscillation See Fig. 2.	2.7 to 5.5		32.768		kHz

Allowable Operating Conditions at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Note 2-1: V_{DD} must be held greater than or equal to 3.0V in the flash ROM onboard programming mode.

Note 2-2: Relationship between tCYC and oscillation frequency is 3/FmCF at a division ratio of 1/1 and 6/FmCF at a division ratio of 1/2.

Note 2-3: See Tables 1 and 2 for the oscillation constants.

Electrical Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Deremeter	Cumhal	Din/Domorko	Conditions			Specificati	on	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High level input current	I _{IH} (1)	Ports 0, 1, 2, 3, 7 RES PWM0, PWM1 D+, D-	Output disabled Pull-up resistor off VIN=VDD (Including output Tr's off leakage current)	2.7 to 5.5			1	
	I _{IH} (2)	XT1, XT2	Input port configuration VIN=VDD	2.7 to 5.5			1	
	I _{IH} (3)	CF1	V _{IN} =V _{DD}	2.7 to 5.5			15	
Low level input current	I _{IL} (1)	Ports 0, 1, 2, 3, 7 RES PWM0, PWM1 D+, D-	Output disabled Pull-up resistor off VIN=VSS (Including output Tr's off leakage current)	2.7 to 5.5	-1			μA
	I _{IL} (2)	XT1, XT2	Input port configuration ^V IN ^{=V} SS	2.7 to 5.5	-1			
	I _{IL} (3)	CF1	VIN=VSS	2.7 to 5.5	-15			
High level output	V _{OH} (1)	Ports 0, 1, 2, 3	I _{OH} =-1mA	4.5 to 5.5	V _{DD} -1			
voltage	V _{OH} (2)	P71 to P73	I _{OH} =-0.4mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (3)		I _{OH} =-0.2mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (4)	PWM0, WM1	I _{OH} =-10mA	4.5 to 5.5	V _{DD} -1.5			
	V _{OH} (5)	P05(CKO when using system clock	I _{OH} =-1.6mA	3.0 to 5.5	V _{DD} -0.4			
	V _{OH} (6)	output function)	I _{OH} =-1mA	2.7 to 5.5	V _{DD} -0.4			
	V _{OH} (7)	PWM0, P01 (when using high current driver)	I _{OH} =-30mA	4.5 to 5.5	V _{DD} -0.5	V _{DD} -0.15		
Low level output	V _{OL} (1)	P00, P01	I _{OL} =30mA	4.5 to 5.5			1.5	v
voltage	V _{OL} (2)		I _{OL} =5mA	3.0 to 5.5			0.4	v
	V _{OL} (3)		I _{OL} =2.5mA	2.7 to 5.5			0.4	
	V _{OL} (4)	Ports 0, 1, 2	I _{OL} =10mA	4.5 to 5.5			1.5	
	V _{OL} (5)	PWM0, PWM1	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (6)	XT2	I _{OL} =1mA	2.7 to 5.5			0.4	
	V _{OL} (7)	Ports 3, 7	I _{OL} =1.6mA	3.0 to 5.5			0.4	
	V _{OL} (8)		I _{OL} =1mA	2.7 to 5.5			0.4	
	V _{OL} (9)	PWM1, P00, P02 (when using high current driver)	I _{OL} =30mA	4.5 to 5.5		0.15	0.5	
Pull-up resistance	Rpu(1)	Ports 0, 1, 2, 3, 7	V _{OH} =0.9V _{DD}	4.5 to 5.5	15	35	80	1.0
	Rpu(2)			2.7 to 5.5	18	50	150	kΩ
Hysteresis voltage	VHYS	RES Port 1, 2, 3, 7		2.7 to 5.5		0.1V _{DD}		V
Pin capacitance	СР	All pins	For pins other than that under test: VIN=VSS f=1MHz Ta=25°C	2.7 to 5.5		10		pF

Serial I/O Characteristics at $Ta=-40^{\circ}C$ to $+85^{\circ}C,\,V_{SS}1=V_{SS}2=V_{SS}3=0V$

1. SIO0 Serial I/O Characteristics (Note 4-1-1)

	Parameter	Symbol	Pin/	Conditions			Speci	ification	
	arameter	Gymbol	Remarks		V _{DD} [V]	min	typ	max	unit
	Frequency	tSCK(1)	SCK0(P12)	See Fig. 8.		2			
	Low level	tSCKL(1)				1			
	High level pulse width	tSCKH(1)				1			
ock		tSCKHA(1a)		 Continuous data transmission/ reception mode USB nor SIO4 are not in use simultaneous. See Fig. 8. 	-	4			
Input clock		tSCKHA(1b)		 (Note 4-1-2) Continuous data transmission/ reception mode USB is in use simultaneous SIO4 is not in use simultaneous. See Fig. 8. (Note 4-1-2) 	2.7 to 5.5	7			tCYC
CLOCK		tSCKHA(1c)		 Continuous data transmission/ reception mode USB and SIO4 are in use simultaneous. See Fig. 8. (Note 4-1-2) 		9			
	Frequency	tSCK(2)	SCK0(P12)	CMOS output selected See Fig. 8.		4/3			
	Low level	tSCKL(2)					1/2		
	pulse width High level	tSCKH(2)					1/2		tSC⊭
Output clock	pulse width	tSCKHA(2a)		 Continuous data transmission/ reception mode USB nor SIO4 are not in use simultaneous. CMOS output selected See Fig. 8. 	0.74-55	tSCKH(2) +2tCYC		tSCKH(2) +(10/3) tCYC	
Outpu		tSCKHA(2b)		 Continuous data transmission/ reception mode USB is in use simultaneous SIO4 is not in use simultaneous. CMOS output selected See Fig. 8. 	- 2.7 to 5.5	tSCKH(2) +2tCYC		tSCKH(2) +(19/3) tCYC	tCYC
		tSCKHA(2c)		 Continuous data transmission/ reception mode USB and SIO4 are in use simultaneous. CMOS output selected See Fig. 8. 		tSCKH(2) +2tCYC		tSCKH(2) +(25/3) tCYC	

Note 4-1-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-1-2: To use serial-clock-input in continuous trans/rec mode, a time from SIORUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Continued on next page.

		arameter	Cumb al	Pin/	Conditions			Speci	ification	
	Р	rarameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
input	Da	ta setup time	tsDI(1)	SB0(P11), SI0(P11)	 Must be specified with respect to rising edge of SIOCLK. See Fig. 8. 		0.03			
Serial input	Da	ta hold time	thDI(1)			2.7 to 5.5	0.03			
	Input clock	Output delay time	tdD0(1)	SO0(P10), SB0(P11)	 Continuous data transmission/ reception mode (Note 4-1-3) 				(1/3)tCYC +0.05	μs
Serial output	Input		tdD0(2)		Synchronous 8-bit mode (Note 4-1-3)	2.7 to 5.5			1tCYC +0.05	
Seria	Output clock		tdD0(3)		(Note 4-1-3)				(1/3)tCYC +0.05	

Note 4-1-3: Must be specified with respect to falling edge of SIOCLK.

Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 8.

		Parameter	Sumbol	Pin/	Conditions			Speci	fication	
		Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
	×	Frequency	tSCK(3)	SCK1(P15)	See Fig. 8.		2			
	Input clock	Low level pulse width	tSCKL(3)			2.7 to 5.5	1			
clock	ľ	High level pulse width	tSCKH(3)				1			tCYC
Serial clock	ş	Frequency	tSCK(4)	SCK1(P15)	When CMOS output type is selected		2			
	Output clock	Low level pulse width	tSCKL(4)		• See Fig. 8.	2.7 to 5.5		1/2		10014
	no	High level pulse width	tSCKH(4)					1/2		tSCK
Serial input	Da	ata setup time	tsDI(2)	SB1(P14), SI1(P14)	 Must be specified with respect to rising edge of SIOCLK. See Fig. 8. 		(1/3)tCYC +0.01			
Serial	Da	ata hold time	thDI(2)			2.7 to 5.5	0.01			
Serial output	O	utput delay time	tdD0(4)	SO1(P13), SB1(P14)	 Must be specified with respect to falling edge of SIOCLK. Must be specified as the time to the beginning of output state change in open drain output mode. See Fig. 8. 	2.7 to 5.5			(1/2)tCYC +0.05	μs

2. SIO1 Serial I/O Characteristics (Note 4-2-1)

Note 4-2-1: These specifications are theoretical values. Add margin depending on its use.

3. SIO4 Serial I/O Characteristics (Note 4-3-1)

I	Parameter	Symbol	Pin/	Conditions	r			ification	
	1	-	Remarks		V _{DD} [V]	min	typ	max	unit
	Frequency	tSCK(5)	SCK4(P24)	See Fig.8.		2			
	Low level pulse width	tSCKL(5)				1			
	High level pulse width	tSCKH(5)				1			
clock		tSCKHA(5a)		 USB nor continuous data transmission/reception mode of SIO0 are not in use simultaneous. See Fig.8. (Note 4-3-2) 	-	4			
Input clock		tSCKHA(5b)		 USB is in use simultaneous. Do not use SIO0 continuous data transmission mode at the same time. See Fig.8. (Note 4-3-2) 	- 2.7 to 5.5	7			tCYC
		tSCKHA(5c)		 USB and continuous data transmission/ reception mode of SIO0 are in use simultaneous. See Fig.8. (Note 4-3-2) 		10			
	Frequency	tSCK(6)	SCK4(P24)	CMOS output selected See Fig.8		4/3			
	Low level pulse width	tSCKL(6)					1/2		
	High level pulse width	tSCKH(6)					1/2		tSCK
clock		tSCKHA(6a)		USB nor continuous data transmission/reception mode of SIO0 are not in use simultaneous. CMOS output selected See Fig.8.		tSCKH(6) +(5/3) tCYC		tSCKH(6) +(10/3) tCYC	
Output clock		tSCKHA(6b)		 USB is in use simultaneous. Do not use SIO0 continuous data transmission mode at the same time. CMOS output selected See Fig8. 	- 2.7 to 5.5	tSCKH(6) +(5/3) tCYC		tSCKH(6) +(19/3) tCYC	tCYC
		tSCKHA(6c)		USB and continuous data transmission/reception mode of SIO0 are in use simultaneous. CMOS output selected See Fig.8.		tSCKH(6) +(5/3) tCYC		tSCKH(6) +(28/3) tCYC	
	ata setup time	tsDI(3)	SO4(P22), SI4(P23)	Must be specified with respect to rising edge of SIOCLK. See Fig.8.	2.7 to 5.5	0.03			
Da	ata hold time	thDI(3)			2.7 to 5.5	0.03			μs

Note 4-3-1: These specifications are theoretical values. Add margin depending on its use.

Note 4-3-2: To use serial-clock-input in continuous trans/rec mode, a time from SI4RUN being set when serial clock is "H" to the first negative edge of the serial clock must be longer than tSCKHA.

Continued on next page.

Continued from preceding page. Pin/ Specification Parameter Symbol Conditions Remarks V_{DD}[V] min typ max unit Output delay time tdD0(5) SO4(P22), Must be specified with SI4(P23) respect to rising edge of Serial output SIOCLK. (1/3)tCYC • Must be specified as the time 2.7 to 5.5 μs to the beginning of output state +0.05 change in open drain output mode. • See Fig.8.

Pulse Input Conditions at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Descenter	Ourschal	Dia (Derserle	Ormalitiener	_		Speci	fication	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
High/low level pulse width	tP1H(1) tP1L(1)	INT0(P70), INT1(P71), INT2(P72), INT4(P20 to P23), INT5(P24 to P27), INT6(P20), INT7(P24)	 Interrupt source flag can be set. Event inputs for timer 0 or 1 are enabled. 	2.7 to 5.5	1			
	tPIH(2) tPIL(2)	INT3(P73) when noise filter time constant is 1/1	 Interrupt source flag can be set. Event inputs for timer 0 are enabled. 	2.7 to 5.5	2			tCYC
	tPIH(3) tPIL(3)	INT3(P73) when noise filter time constant is 1/32	 Interrupt source flag can be set. Event inputs for timer 0 are nabled. 	2.7 to 5.5	64			
	tPIH(4) tPIL(4)	INT3(P73) when noise filter time constant is 1/128	 Interrupt source flag can be set. Event inputs for timer 0 are enabled. 	2.7 to 5.5	256			
	tPIL(5)	RES	Resetting is enabled.	2.7 to 5.5	200			μs

AD Converter Characteristics at Ta = -40°C to +85°C, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

<12-bits AD Converter Mode>

Demonster	Querra ha a l	Dia /D a sta a sta	Oraditions			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	Ν	AN0(P00) to		3.0 to 5.5		12		bit
Absolute accuracy	ET	AN7(P07), AN8(PWM1),	(Note 6-1)	3.0 to 5.5			±16	LSB
Conversion time	TCAD	AN9(PWM0),	See conversion time calculation	4.5 to 5.5	32		115	
		AN10(XT1), AN11(XT2),	formulas. (Note 6-2)	3.0 to 5.5	64		115	μs
Analog input voltage range	VAIN	AN12(P20) to AN19(P27)		3.0 to 5.5	V _{SS}		V _{DD}	V
Analog port	IAINH		VAIN=V _{DD}	3.0 to 5.5			1	
input current	put current IAINL	VAIN=V _{SS}	3.0 to 5.5	-1			μA	

<8-bits AD Converter Mode>

Deservation	O maked	Pin/Remarks	Operativitana			Specifi	cation	
Parameter	Symbol	Pin/Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
Resolution	Ν	AN0(P00) to		3.0 to 5.5		8		bit
Absolute accuracy	ET	AN7(P07), AN8(PWM1),	(Note 6-1)	3.0 to 5.5			±1.5	LSB
Conversion time	TCAD	AN9(PWM0),	See conversion time calculation	4.5 to 5.5	20		90	
		AN10(XT1), AN11(XT2),	formulas. (Note 6-2)	3.0 to 5.5	40		90	μs
Analog input voltage range	VAIN	AN12(P20) to AN19(P27)		3.0 to 5.5	V _{SS}		V _{DD}	V
Analog port	IAINH		VAIN=V _{DD}	3.0 to 5.5			1	
input current	IAINL		VAIN=V _{SS}	3.0 to 5.5	-1			μA

Conversion time calculation formulas :

12-bits AD Converter Mode : TCAD (Conversion time) = $((52/(AD \text{ division ratio}))+2) \times (1/3) \times tCYC$ 8-bits AD Converter Mode : TCAD (Conversion time) = $((32/(AD \text{ division ratio}))+2) \times (1/3) \times tCYC$

<Recommended Operating Conditions>

External oscillator	Supply Voltage	System Clock Division	Cycle Time	AD Frequency Division Ratio	Conversion Time (TCAD)[µs]		
FmCF[MHz]	Range V _{DD} [V]	(SYSDIV)	tCYC [ns]	(ADDIV)	12-bit AD	8-bit AD	
40	4.0 to 5.5	1/1	250	1/8	34.8	21.5	
12	3.0 to 5.5	1/1	250	1/16	69.5	42.8	

Note 6-1: The quantization error (±1/2LSB) must be excluded from the absolute accuracy. The absolute accuracy must be measured in the microcontroller's state in which no I/O operations occur at the pins adjacent to the analog input channel.

Note 6-2: The conversion time refers to the period from the time an instruction for starting a conversion process till the time the conversion results register(s) are loaded with a complete digital conversion value corresponding to the analog input value.

The conversion time is 2 times the normal-time conversion time when:

• The first AD conversion is performed in the 12-bit AD conversion mode after a system reset.

• The first AD conversion is performed after the AD conversion mode is switched from 8-bit to 12-bit conversion mode.

					Specifi	cation		
Parameter	Symbol	Conditions	Option selected voltage	min	typ	max	unit	
POR release voltage	PORRL	Select from option	2.57V	2.45	2.57	2.69		
		(Note 7-1)	2.87V	2.75	2.87	2.99		
			3.86V	3.73	3.86	3.99	V	
			4.35V	4.21	4.35	4.49	v	
Detection voltage unknown state	POUKS	See Fig.11 (Note 7-2)			0.7	0.95		
Power supply rise time	PORIS	Power supply rise time from 0V to 1.6V				100	ms	

Power-on Reset (POR) Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Note 7-1: The POR release level can be selected out of 4 levels only when the LVD reset function is disabled. Note 7-2: POR is in unknown state before transistor start operation.

Low Voltage Detection Reset (LVD) Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

					Specifi	ication		
Parameter	Symbol	Conditions	Option selected voltage	min	typ	max	unit	
LVD reset voltage	LVDET	Select from option	2.81V	2.71	2.81	2.91		
(Note 8-2)		See Fig.12	3.79V	3.69	3.79	3.89	V	
		(Note 8-1) (Note 8-3)	4.28V	4.18	4.28	4.38		
LVD hysteresis width	LVHYS	(10018-0-3)	2.81V		55			
			3.79V		60		mV	
			4.28V		60			
Detection voltage unknown state	LVUKS	See Fig.12 (Note 8-4)			0.7	0.95	V	
Low voltage detection minimum width (Reply sensitivity).	TLVDW	LVDET-0.5V See Fig.13		0.2			ms	

Note 8-1: The LVD reset level can be selected out of 3 levels only when the LVD reset function is enabled.

Note 8-2: LVD reset voltage specification values do not include hysteresis voltage.

Note 8-3: LVD reset voltage may exceed its specification values when port output state changes and and/or when a large current flows through port.

Note 8-4: LVD is in unknown state before transistor start operation.

Consumption Current Characteristics at $Ta = -40^{\circ}C$ to $+85^{\circ}C$, $V_{SS}1 = V_{SS}2 = V_{SS}3 = 0V$

Parameter	Symbol	Pin/	Conditions	r		Specif	ication	-
	,	Remarks		V _{DD} [V]	min	typ	max	unit
Normal mode consumption current (Note 9-1)	IDDOP(1)	V _{DD} 1 =V _{DD} 2 =V _{DD} 3	 FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side Internal PLL oscillation stopped 	4.5 to 5.5		8.8	16	
(Note 9-2)	IDDOP(2)		 Internal RC oscillation stopped USB circuit stopped 1/1 frequency division ratio 	3.0 to 3.6		5.1	9.2	
	IDDOP(3)		FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		13	23	
	IDDOP(4)		 Internal PLL oscillation mode active Internal RC oscillation stopped USB circuit active 1/1 frequency division ratio 	3.0 to 3.6		7.0	13	mA
	IDDOP(5)		• FmCF=12MHz ceramic oscillation mode	4.5 to 5.5		5.6	9.5	
	IDDOP(6)		 FsX'tal=32.768kHz crystal oscillation mode System clock set to 6MHz side 	3.0 to 3.6		3.6	6.0	
	IDDOP(7)		 Internal RC oscillation stopped 1/2 frequency division ratio 	2.7 to 3.0		3.0	4.8	
	IDDOP(8)		FmCF=0Hz(oscillation stopped)	4.5 to 5.5		0.76	2.8	
	IDDOP(9)		 FsX'tal=32.768kHz crystal oscillation mode System clock set to internal RC oscillation 	3.0 to 3.6		0.43	1.5	
	IDDOP(10)		• 1/2 frequency division ratio	2.7 to 3.0		0.36	1.2	
	IDDOP(11)		 FmCF=0Hz(oscillation stopped) FsX'tal=32.768kHz crystal oscillation mode 	4.5 to 5.5		48	140	
	IDDOP(12)		 System clock set to crystal oscillation. (32.768kHz) 	3.0 to 3.6		18	55	μΑ
	IDDOP(13)		 Internal RC oscillation stopped 1/2 frequency division ratio 	2.7 to 3.0		14	40	
HALT mode consumption current (Note9-1)	IDDHALT(1)		HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		4.3	7.6	
(Note9-2)	IDDHALT(2)		 Internal PLL oscillation stopped Internal RC oscillation stopped USB circuit stopped 1/1 frequency division ratio 	3.0 to 3.6		2.2	4.0	
	IDDHALT(3)		HALT mode FmCF=12MHz ceramic oscillation mode FsX'tal=32.768kHz crystal oscillation mode System clock set to 12MHz side	4.5 to 5.5		8.1	15	
	IDDHALT(4)		 Internal PLL oscillation mode active Internal RC oscillation stopped USB circuit active 1/1 frequency division ratio 	3.0 to 3.6		4.2	7.5	mA
	IDDHALT(5)		HALT mode FmCF=12MHz ceramic oscillation mode	4.5 to 5.5		2.7	4.8	
	IDDHALT(6)		 FsX'tal=32.768kHz crystal oscillation mode System clock set to 6MHz side 	3.0 to 3.6		1.3	2.4	-
	IDDHALT(7)		 Internal RC oscillation stopped 1/2 frequency division ratio 	2.7 to 3.0		1.1	1.8	
	IDDHALT(8)]	HALT mode Face (In the stand of the	4.5 to 5.5		0.48	1.9	
	IDDHALT(9)	1	 FmCF=0Hz(oscillation stopped) FsX'tal=32.768kHz crystal oscillation mode 	3.0 to 3.6		0.22	0.81	
		1	 System clock set to internal RC oscillation. 					

Note 9-1: The consumption current value includes none of the currents that flow into the output transistors and internal pull-up resistors.

Note9-2: Unless otherwise specified, the consumption current for the LVD circuits is not included.

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Devenueter	Ourseland.	Pin/	O an dition a			Specif	ication	
Parameter	Symbol	Remarks	Conditions	V _{DD} [V]	min	typ	max	unit
HALT mode consumption	IDDHALT(11)	V _{DD} 1 =V _{DD} 2	HALT mode FmCF=0MHz (oscillation stopped)	4.5 to 5.5		35	120	
current (Note 9-1)	IDDHALT(12)	=V _{DD} 3	 FsX'tal=32.768kHz crystal oscillation mode System clock set to crystal oscillation. 	3.0 to 3.6		9.5	39	
(Note 9-2)	IDDHALT(13)		(32.768kHz)Internal RC oscillation stopped1/2 frequency division ratio	2.7 to 3.0		6.4	27	
HOLD mode	IDDHOLD(1)	V _{DD} 1	HOLD mode	4.5 to 5.5		0.08	24	
consumption	IDDHOLD(2)		 CF1=V_{DD} or open (External clock mode) 	3.0 to 3.6		0.03	11	
current (Note 9-1) (Note 9-2)	IDDHOLD(3)			2.7 to 3.0		0.02	9.6	
	IDDHOLD(4)		HOLD mode	4.5 to 5.5		2.9	29	
,	IDDHOLD(5)		LVD option selected	3.0 to 3.6		2.2	15	μA
	IDDHOLD(6)		 CF1=V_{DD} or open (External clock mode) 	2.7 to 3.0		2.1	12	•
	IDDHOLD(7)		HOLD mode	4.5 to 5.5		2.9	32	
	IDDHOLD(8)		 Watchdog timer operation mode (internal low-speed RC oscillation circuit 	3.0 to 3.6		1.4	16	
	IDDHOLD(9)		operation) • CF1=V _{DD} or open (External clock mode)	2.7 to 3.0		1.2	14	
imer HOLD	IDDHOLD(10)		Timer HOLD mode CF1=V _{DD} or open (External clock mode)	4.5 to 5.5		31	110	
consumption	IDDHOLD(11)		FsX'tal=32.768kHz crystal oscillation mode	3.0 to 3.6		7.0	34	
Note 9-1) Note 9-2)	IDDHOLD(12)			2.7 to 3.0		4.3	22	

Note 9-1: The consumption current value includes none of the currents that flow into the output transistors and internal pull-up resistors.

Note9-2: Unless otherwise specified, the consumption current for the LVD circuits is not included.

USB Characteristics and Timing at $Ta=-40^{\circ}C$ to $+85^{\circ}C,\,V_{SS}1=V_{SS}2=V_{SS}3=0V$

Deservator	Question	Qualitiers		Specif	ication	
Parameter	Symbol	Conditions	min	typ	max	unit
High level output	VOH(USB)	• 15kΩ±5% to GND	2.8		3.6	V
Low level output	VOL(USB)	• 1.5kΩ±5% to 3.6V	0.0		0.3	V
Output signal crossover voltage	VCRS		1.3		2.0	V
Differential input sensitivity	V _{DI}	• (D+)-(D-)	0.2			V
Differential input common mode range	V _{CM}		0.8		2.5	V
High level input	VIH(USB)		2.0			V
Low level input	VIL(USB)				0.8	V
USB data rise time	^t R	• R _S =27 to 33Ω, C _L =50pF • V _{DD} 3=3.0 to 3.6V	4		20	ns
USB data fall time tF		• R _S =27 to 33Ω, C _L =50pF • V _{DD} 3=3.0 to 3.6V	4		20	ns

F-ROM Programming Characteristics at $Ta = +10^{\circ}C$ to $+55^{\circ}C$, $V_{SS}1 = 0V$

Descenter	O mark al	Pin/	Que distante		Specification			
Parameter	Symbol Remarks		Conditions	V _{DD} [V]	min	typ	max	unit
Onboard programming current	IDDFW(1)	V _{DD} 1	 Excluding power dissipation in the microcontroller block 	3.0 to 5.5		5	10	mA
Programming time	tFW(1)		Erase operation	0.01.55		20	30	ms
	tFW(2)	Write operation		3.0 to 5.5		40	60	μs

Characteristics of a Sample Main System Clock Oscillation Circuit

Given below are the characteristics of a sample main system clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Table 1 Characteristics of a Sample Main System Clock Oscillator Circuit with a Ceramic Oscillator at Ta = -40° C to $+85^{\circ}$ C

ut 1	$a = -40 \ C \ 10$	105 0							
Nominal	Vendor		Cir	cuit Const	ant	Operating Voltage		lation tion Time	Demeric
Frequency	Name	Oscillator Name	C1 [pF]	C2 [pF]	Rd1 [Ω]	Range [V]	typ [ms]	max [ms]	Remarks
12MHz	MURATA	CSTCE12M0GH5L**-R0	(33)	(33)	470	3.0 to 5.5	0.1	0.5	C1 and C2 integrated SMD type

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in the following cases (see Figure 4):

- Till the oscillation gets stabilized after VDD goes above the operating voltage lower limit.
- Till the oscillation gets stabilized after the instruction for starting the main clock oscillation circuit is executed.
- Till the oscillation gets stabilized after the HOLD mode is reset.
- Till the oscillation gets stabilized after the X'tal HOLD mode is reset with CFSTOP (OCR register, bit 0) set to 0.

Characteristics of a Sample Subsystem Clock Oscillator Circuit

Given below are the characteristics of a sample subsystem clock oscillation circuit that are measured using a Our designated oscillation characteristics evaluation board and external components with circuit constant values with which the oscillator vendor confirmed normal and stable oscillation.

Nominal	Vendor	O sillatas Nama		Circuit C	Constant		Operating Voltage	Oscil Stabilizat	lation tion Time	Demeric
Frequency	Name	Oscillator Name	C3 C		Rf	Rd2	Range	typ max		Remarks
			[pF]	[pF]	[Ω]	[Ω]	[V]	[s]	[s]	
32.768kHz	EPSON TOYOCOM	MC-306	18	18	OPEN	680k	2.7 to 5.5	1.1	3.0	Applicable CL value=12.5pF SMD type

Table 2 Characteristics of a Sample Subsystem Clock Oscillator Circuit with a Crystal Oscillator

The oscillation stabilization time refers to the time interval that is required for the oscillation to get stabilized in the following cases (see Figure 4):

• Till the oscillation gets stabilized after the instruction for starting the subclock oscillation circuit is executed.

• Till the oscillation gets stabilized after the HOLD mode is reset with EXTOSC (OCR register, bit 6) set to 1.

Note: The components that are involved in oscillation should be placed as close to the IC and to one another as possible because they are vulnerable to the influences of the circuit pattern.



Figure 1 CF Oscillator Circuit



Figure 2 Crystal Oscillator Circuit



Figure 3 AC Timing Measurement Point



Reset Time and Oscillation Stabilization Time



HOLD Reset Signal and Oscillation Stabilization Time

Figure 4 Oscillation Stabilization Time



When using the internal PLL circuit to generate the-48MHz clock for USB, it is necessary to connect a filter circuit such as that shown to the left to the P34/UFILT pin.

After PLL settings, 20ms or more is required to stabilize.





Note:

It's necessary to adjust the Circuit Constant of the USB Port Peripheral Circuit each mounting board. Make the D+ Pull-up resistors available to control on/off according to the Vbus.









Figure 8 Serial Input/Output Waveform



Figure 9 Pulse Input Timing Signal Waveform



Figure 10 USB Data Signal Timing and Voltage Level



Figure 11 Example of POR Only (LVD Deselected) Mode Waveforms (at Reset Pin with RRES Pull-up Resistor Only)

- The POR function generates a reset only when the power voltage goes up from the VSS level.
- No stable reset will be generated if power is turned on again when the power level does not go down to the VSS level as shown in (a). If such a case is anticipated, use the LVD function together with the POR function as shown below or implement an external reset circuit.
- A reset is generated only when the power level goes down to the VSS level as shown in (b) and power is turned on again after this condition continues for 100µs or longer.



Figure 12 Example of POR + LVD Mode Waveforms (at Reset Pin with RRES Pull-up Resistor Only)

- Reset are generated both when power is turned on and when the power level lowers.
- A hysteresis width (LVHYS) is provided to prevent the repetitions of reset release and entry cycles near the detection level.



Figure 13 Minimum Low Voltage Detection Width (Example of Voltage Sag/Fluctuation Waveform)

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